

CMD5950-VB Datasheet

P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	- 100			
$R_{DS(on)} (\Omega)$ at $V_{GS} = -10 V$	0.033			
$R_{DS(on)} (\Omega)$ at $V_{GS} = -4.5 V$	0.037			
I _D (A)	- 40			
Configuration	Single			

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- Package with Low Thermal Resistance
- 100 % $\rm R_g$ and UIS Tested

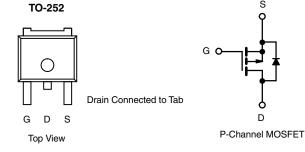
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• Compliant to RoHS Directive 2002/95/EC



RoHS COMPLIANT HALOGEN FREE



ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V _{DS}	- 100	v			
Gate-Source Voltage	V _{GS}	± 20	v			
Continuous Drain Current	T _C = 25 °C	- I _D	- 40			
	T _C = 125 °C		- 22			
Continuous Source Current (Diode Conductio	I _S	- 50	А			
Pulsed Drain Current ^b	I _{DM}	- 150				
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	- 44			
Single Pulse Avalanche Energy	L = 0.1 MH	E _{AS}	96	mJ		
Maximum Power Dissipation ^b	T _C = 25 °C	PD	136	w		
	T _C = 125 °C		45			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	50	°C/W		
Junction-to-Case (Drain)		R _{thJC}	1.1	C/ W		

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.

SPECIFICATIONS ($T_c = 25 \text{ °C}$, unless otherwise noted)									
PARAMETER	SYMBOL	TES	TEST CONDITIONS		TEST CONDITIONS		TYP.	MAX.	UNIT
Static									
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = -250 \mu A$		- 100	-	-	v		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V_{GS} , I_D = - 250 μ A	- 1.0	-	-2.5	v		
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$		-	± 100	nA		
		$V_{GS} = 0 V$	V _{DS} = - 100 V	-	-	- 1			
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V_{DS} = - 100 V, T _J = 125 °C	-	-	- 50	μA		
		$V_{GS} = 0 V$	V_{DS} = - 100 V, T _J = 175 °C	-	-	- 250	1		
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = -10 V$	$V_{DS} \le$ - 5 V	- 30	-	-	А		
		V _{GS} = - 10 V	I _D = - 9.2 A	-	0.033	-	Ω		
Ducia Course On Ototo Desistence	P	V _{GS} = - 10 V	I _D = - 9.2 A, T _J = 125 °C	-	0.065	-			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 9.2 A, T _J = 175 °C	-	0.081	-			
		$V_{GS} = -4.5 V$	I _D = - 7.7 A	-	0.037	-			
Forward Transconductance ^b	9 _{fs}	V _{DS} =	V _{DS} = - 15 V, I _D = - 9.2 A		35	-	S		
Dynamic ^b		·			-		-		
Input Capacitance	C _{iss}			-	4433	-			
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = - 25 V, f = 1 MHz	-	301	-	pF		
Reverse Transfer Capacitance	C _{rss}			-	208	-			
Total Gate Charge ^c	Qg			-	96	144	nC		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = - 10 V	$V_{DS} = -50V, I_{D} = -9.2 \text{ A}$	-	8.4	-			
Gate-Drain Charge ^c	Q _{gd}			-	23.5	-			
Gate Resistance	R _g	f = 1 MHz		1.5	3.13	4.7	Ω		
Turn-On Delay Time ^c	t _{d(on)}	V_{DD} = - 50 V, R _L = 6.49 Ω I _D \cong - 7.7 A, V _{GEN} = - 10 V, R _g = 1.0 Ω		-	11	17			
Rise Time ^c	t _r			-	11	17	ns		
Turn-Off Delay Time ^c	t _{d(off)}			-	78	117			
Fall Time ^c	t _f			-	15	23			
Source-Drain Diode Ratings and Characteristics ^b									
Pulsed Current ^a	I _{SM}			-	-	- 150	Α		
Forward Voltage	V _{SD}	I _F = - 7.7 A, V _{GS} = 0 V		-	- 0.8	- 1.5	V		

Notes

a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

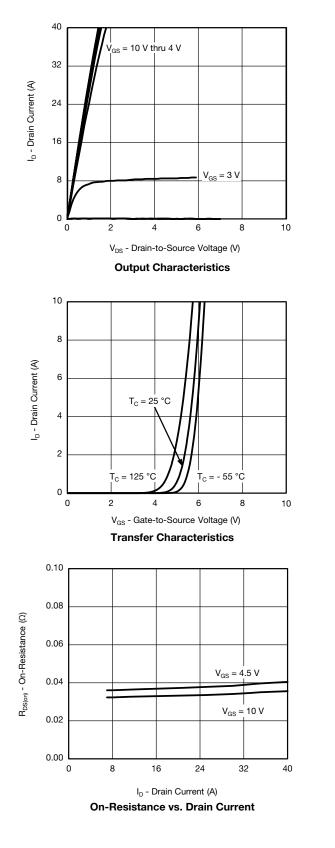
c. Independent of operating temperature.

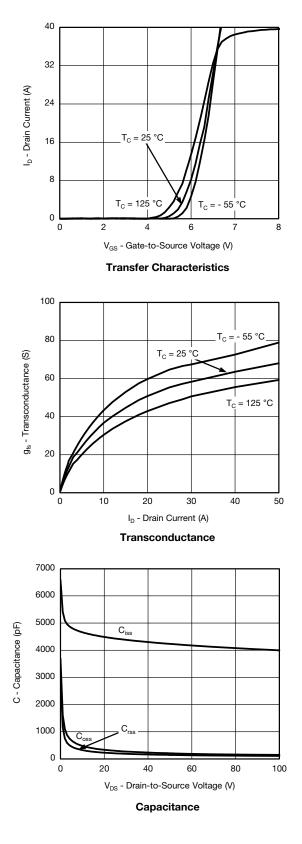
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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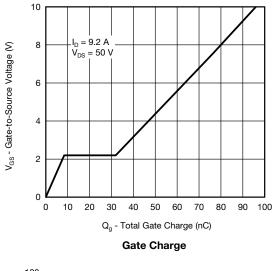
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)

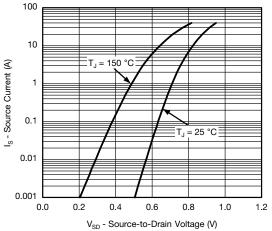




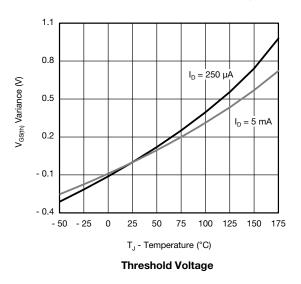


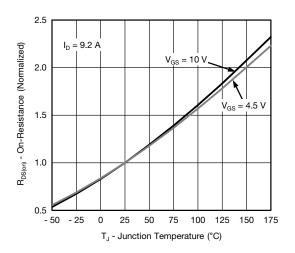
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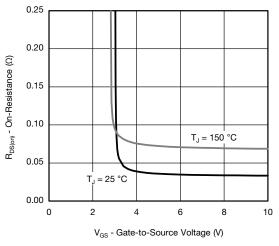


Source Drain Diode Forward Voltage

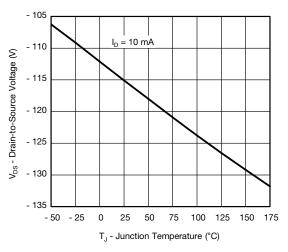




On-Resistance vs. Junction Temperature



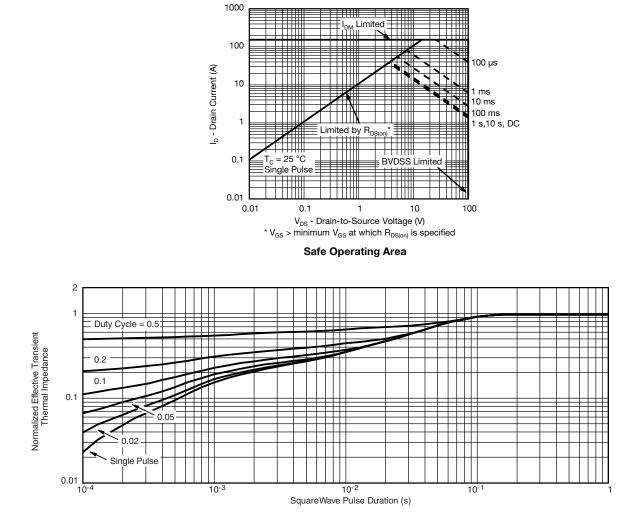
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



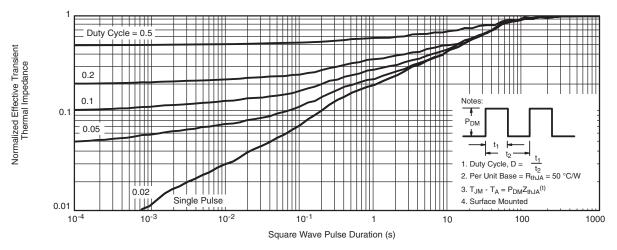
THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case



THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

Note

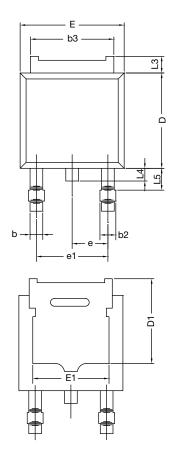
• The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

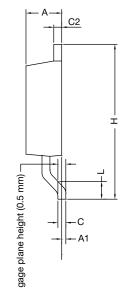
- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.





TO-252AA Case Outline



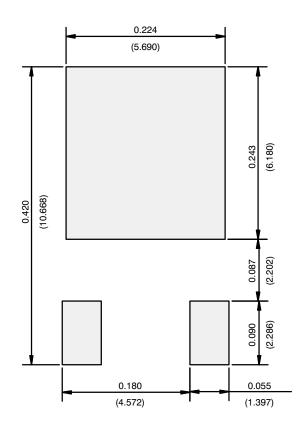
	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	4.10	-	0.161	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.01	1.52	0.040	0.060	
ECN: T13-0592-Rev. A, 02-Sep-13 DWG: 6019					

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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